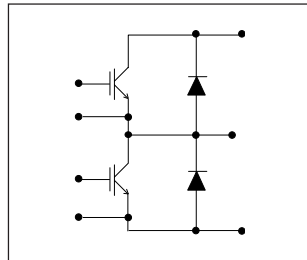


#### Features

- UltraFast Non Punch Through (NPT) Technology
- Positive  $V_{CE(ON)}$  Temperature Coefficient
- 10 $\mu$ s Short Circuit Capability
- HEXFRED™ Antiparallel Diodes with UltraSoft Reverse Recovery
- Low Diode  $V_F$
- Square RBSOA
- Aluminum Nitride DBC
- Optional SMT Thermistor (NTC)
- Very Low Stray Inductance Design for High Speed Operation
- UL approved (file E78996)



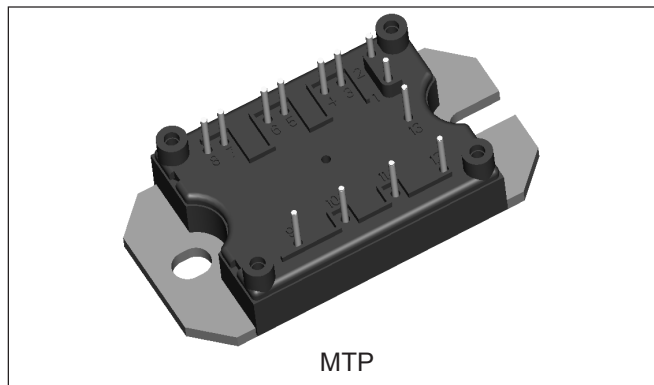
$$V_{CES} = 1200V$$

$$I_C = 80A$$

$$T_C = 25^\circ C$$

#### Benefits

- Optimized for Welding, UPS and SMPS Applications
- Rugged with UltraFast Performance
- Benchmark Efficiency above 20KHz
- Outstanding ZVS and Hard Switching Operation
- Low EMI, requires Less Snubbing
- Excellent Current Sharing in Parallel Operation
- Direct Mounting to Heatsink
- PCB Solderable Terminals



#### Absolute Maximum Ratings

| Parameters |  | Max                   | Units                 |
|------------|--|-----------------------|-----------------------|
| $V_{CES}$  | Collector-to-Emitter Breakdown Voltage                 | 1200                  | V                     |
| $I_C$      | Continuos Collector Current                            | @ $T_C = 25^\circ C$  | 80                    |
|            |  | @ $T_C = 105^\circ C$ | 40                    |
| $I_{CM}$   | Pulsed Collector Current                               | 160                   |                       |
| $I_{LM}$   | Clamped Inductive Load Current                         | 160                   |                       |
| $I_F$      | Diode Continuous Forward Current                       | 21                    | @ $T_C = 105^\circ C$ |
| $I_{FM}$   | Diode Maximum Forward Current                          | 160                   |                       |
| $V_{GE}$   | Gate-to-Emitter Voltage                                | $\pm 20$              | V                     |
| $V_{ISOL}$ | RMS Isolation Voltage, Any Terminal to Case, t = 1 min | 2500                  |                       |
| $P_D$      | Maximum Power Dissipation (only IGBT)                  | @ $T_C = 25^\circ C$  | 463                   |
|            |  | @ $T_C = 100^\circ C$ | 185                   |

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

| Parameters   | Min  | Typ  | Max  | Units | Test Conditions   |
|--|------|------|------|-------|---|
| V <sub>(BR)CES</sub> Collector-to-Emitter Breakdown Voltage                    | 1200 |      |      | V     | V <sub>GE</sub> = 0V, I <sub>C</sub> = 250μA                          |
| ΔV <sub>(BR)CES</sub> /ΔT <sub>J</sub> Temperature Coeff. of Breakdown Voltage |      | +1.1 |      | V/°C  | V <sub>GE</sub> = 0V, I <sub>C</sub> = 3mA (25-125°C)                 |
| V <sub>CE(ON)</sub> Collector-to-Emitter Saturation Voltage                    |      | 3.36 | 3.59 | V     | V <sub>GE</sub> = 15V, I <sub>C</sub> = 40A                           |
|  |      | 4.53 | 4.91 |       | V <sub>GE</sub> = 15V, I <sub>C</sub> = 80A                           |
|  |      | 3.88 | 4.10 |       | V <sub>GE</sub> = 15V, I <sub>C</sub> = 40A T <sub>J</sub> = 150°C    |
|  |      | 5.35 | 5.68 |       | V <sub>GE</sub> = 15V, I <sub>C</sub> = 80A T <sub>J</sub> = 150°C    |
| V <sub>GE(th)</sub> Gate Threshold Voltage                                     | 4    |      | 6    | V     | V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 500μA            |
| ΔV <sub>GE(th)</sub> /ΔT <sub>J</sub> Temperature Coeff. of Threshold Voltage  |      | -12  |      | mV/°C | V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1mA (25-125°C)   |
| g <sub>fe</sub> Transconductance   |      | 35   |      | S     | V <sub>CE</sub> = 50V, I <sub>C</sub> = 40A, PW = 80μs                |
| I <sub>CES</sub> Zero Gate Voltage Collector Current                           |      |      | 250  | μA    | V <sub>GE</sub> = 0V, V <sub>CE</sub> = 1200V, T <sub>J</sub> = 25°C  |
|  |      | 0.4  | 1.0  | mA    | V <sub>GE</sub> = 0V, V <sub>CE</sub> = 1200V, T <sub>J</sub> = 125°C |
|  |      | 0.2  | 10   |       | V <sub>GE</sub> = 0V, V <sub>CE</sub> = 1200V, T <sub>J</sub> = 150°C |
| I <sub>GES</sub> Gate-to-Emitter Leakage Current                               |      |      | ±250 | nA    | V <sub>GE</sub> = ± 20V   |

**Switching Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

| Parameters                                      | Min         | Typ  | Max  | Units | Test Conditions  |
|---|-------------|------|------|-------|--|
| Q <sub>g</sub> Total Gate Charge (turn-on)      |             | 399  | 599  | nC    | I <sub>C</sub> = 40A<br>V <sub>CC</sub> = 600V<br>V <sub>GE</sub> = 15V  |
| Q <sub>ge</sub> Gate-Emitter Charge (turn-on)   |             | 43   | 65   |       |  |
| Q <sub>gc</sub> Gate-Collector Charge (turn-on) |             | 187  | 281  |       |  |
| E <sub>on</sub> Turn-On Switching Loss          |             | 1142 | 1713 | μJ    | V <sub>CC</sub> = 600V, I <sub>C</sub> = 40A<br>V <sub>GE</sub> = 15V, R <sub>g</sub> = 5Ω, L = 200μH<br>T <sub>J</sub> = 25°C, Energy losses include tail and diode reverse recovery  |
| E <sub>off</sub> Turn-Off Switching Loss        |             | 1345 | 2018 |       |  |
| E <sub>tot</sub> Total Switching Loss           |             | 2487 | 3731 |       |  |
| E <sub>on</sub> Turn-On Switching Loss          |             | 1598 | 2397 | μJ    | V <sub>CC</sub> = 600V, I <sub>C</sub> = 40A<br>V <sub>GE</sub> = 15V, R <sub>g</sub> = 5Ω, L = 200μH<br>T <sub>J</sub> = 125°C, Energy losses include tail and diode reverse recovery |
| E <sub>off</sub> Turn-Off Switching Loss        |             | 1618 | 2427 |       |  |
| E <sub>tot</sub> Total Switching Loss           |             | 3216 | 4824 |       |  |
| C <sub>ies</sub> Input Capacitance              |             | 5521 | 8282 | pF    | V <sub>GE</sub> = 0V<br>V <sub>CC</sub> = 30V<br>f = 1.0 MHz   |
| C <sub>oes</sub> Output Capacitance             |             | 380  | 570  |       |  |
| C <sub>res</sub> Reverse Transfer Capacitance   |             | 171  | 257  |       |  |
| RBSOA Reverse Bias Safe Operating Area          | full square |      |      |       | T <sub>J</sub> = 150°C, I <sub>C</sub> = 160A<br>V <sub>CC</sub> = 1000V, V <sub>p</sub> = 1200V<br>R <sub>g</sub> = 5Ω, V <sub>GE</sub> = +15V to 0V                                  |
| SCSOA Short Circuit Safe Operating Area         | 10          |      |      | μs    | T <sub>J</sub> = 150°C<br>V <sub>CC</sub> = 900V, V <sub>p</sub> = 1200V<br>R <sub>g</sub> = 5Ω, V <sub>GE</sub> = +15V to 0V  |

### Diode Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

| Parameters  | Min | Typ  | Max  | Units | Test Conditions                                       |
|---|-----|------|------|-------|---|
| V <sub>FM</sub> Diode Forward Voltage Drop            |     | 2.98 | 3.38 | V     | I <sub>C</sub> = 40A                                  |
|   |     | 3.90 | 4.41 |       | I <sub>C</sub> = 80A                                  |
|   |     | 3.08 | 3.39 |       | I <sub>C</sub> = 40A, T <sub>J</sub> = 125°C          |
|   |     | 4.29 | 4.72 |       | I <sub>C</sub> = 80A, T <sub>J</sub> = 125°C          |
|   |     | 3.12 | 3.42 |       | I <sub>C</sub> = 40A, T <sub>J</sub> = 150°C          |
| E <sub>rec</sub> Reverse Recovery Energy of the Diode |     | 574  | 861  | μJ    | V <sub>GE</sub> = 15V, R <sub>g</sub> = 5Ω, L = 200μH |
| trr Diode Reverse Recovery Time                       |     | 120  | 180  | ns    | V <sub>CC</sub> = 600V, I <sub>C</sub> = 40A          |
| I <sub>rr</sub> Peak Reverse Recovery Current         |     | 43   | 65   | A     | T <sub>J</sub> = 125°C                                |

### Thermistor Specifications (40MT120UHT only)

| Parameters   | Min | Typ  | Max | Units | Test Conditions                                |
|--|-----|------|-----|-------|--|
| R <sub>0</sub> <sup>(1)</sup> Resistance                         |     | 30   |     | kΩ    | T <sub>0</sub> = 25°C                          |
| β <sup>(1)(2)</sup> Sensitivity index of the thermistor material |     | 4000 |     | K     | T <sub>0</sub> = 25°C<br>T <sub>1</sub> = 85°C |

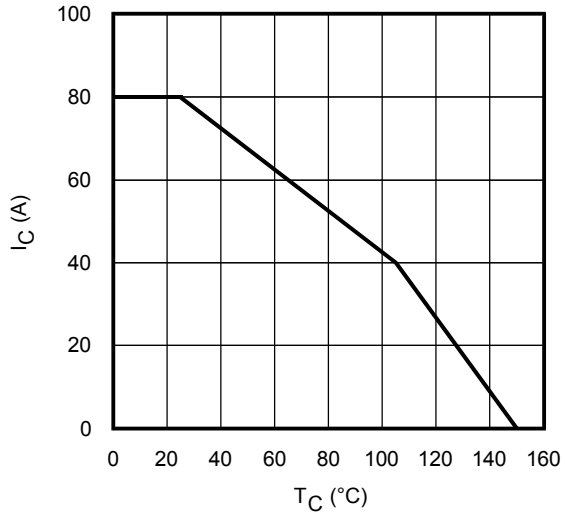
<sup>(1)</sup> T<sub>0</sub>, T<sub>1</sub> are thermistor's temperatures

$$\beta = \frac{R_0}{R_1} = \exp \left[ \beta \left( \frac{1}{T_0} - \frac{1}{T_1} \right) \right], \text{ Temperatures in Kelvin}$$

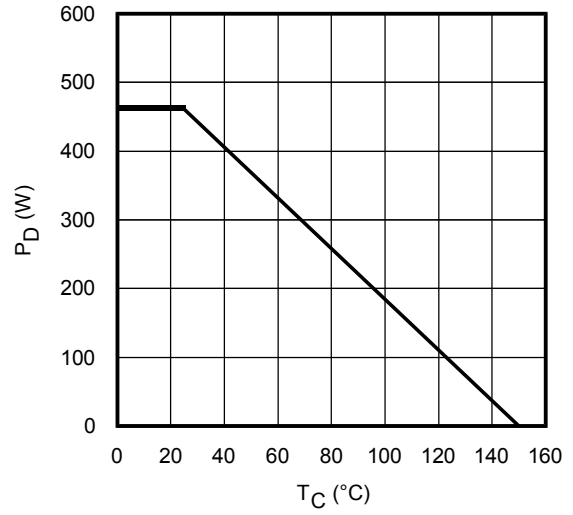
### Thermal- Mechanical Specifications

| Parameters   | Min    | Typ     | Max  | Units  |
|--|--------|---------|------|--------|
| T <sub>J</sub> Operating Junction Temperature Range  | - 40   |         | 150  | °C     |
| T <sub>STG</sub> Storage Temperature Range   | - 40   |         | 125  |        |
| R <sub>thJC</sub> Junction-to-Case   | IGBT   |         | 0.20 | °C/ W  |
|  | Diode  |         | 0.39 |        |
| R <sub>thCS</sub> Case-to-Sink<br>(Heatsink Compound Thermal Conductivity = 1 W/mK)                | Module |         | 0.06 |        |
| Clearance (external shortest distance in air between two terminals)                                | 5.5    |         |      | mm     |
| Creepage (shortest distance along external surface of the insulating material between 2 terminals) | 8      |         |      |        |
| T Mounting torque to heatsink (3)  |        | 3 ± 10% |      | Nm     |
| Wt Weight  |        | 66      |      | g (oz) |

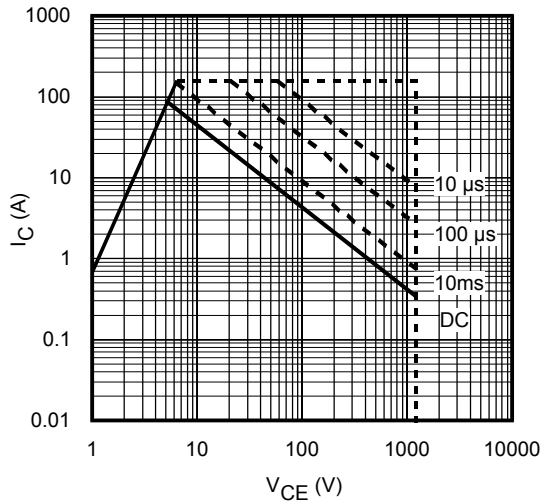
(3) A mounting compound is recommended and the torque should be checked after 3 hours to allow for the spread of the compound. Lubricated threads



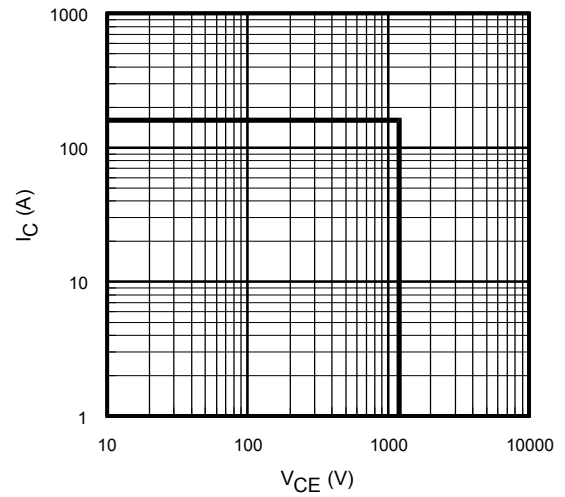
**Fig. 1** - Maximum DC Collector Current vs. Case Temperature



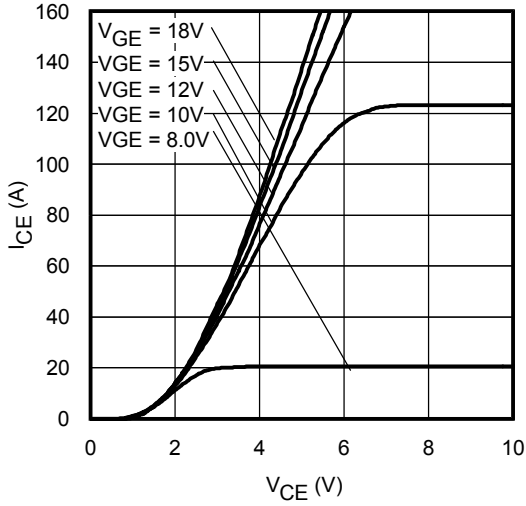
**Fig. 2** - Power Dissipation vs. Case Temperature



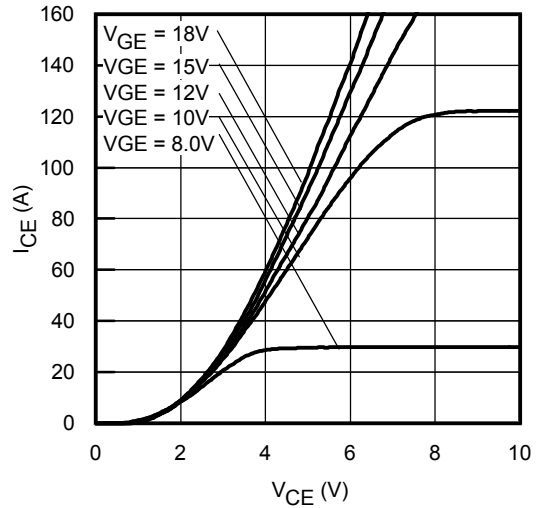
**Fig. 3** - Forward SOA  
 $T_C = 25^\circ\text{C}$ ;  $T_J \leq 150^\circ\text{C}$



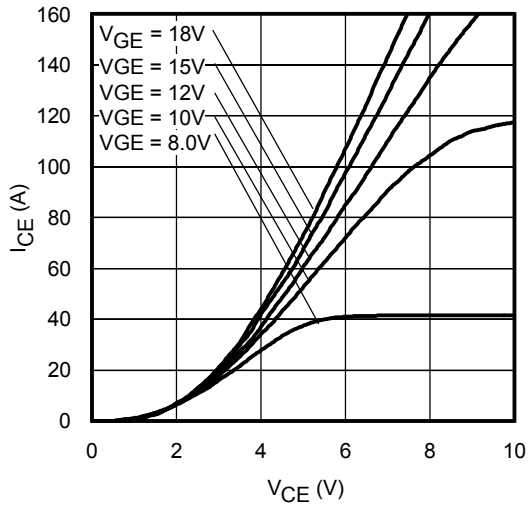
**Fig. 4** - Reverse Bias SOA  
 $T_J = 150^\circ\text{C}$ ;  $V_{GE} = 15\text{V}$



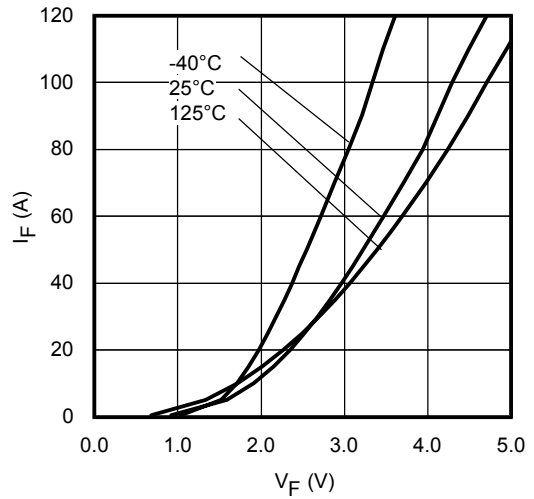
**Fig. 5 - Typ. IGBT Output Characteristics**  
 $T_J = -40^\circ\text{C}; t_p = 80\mu\text{s}$



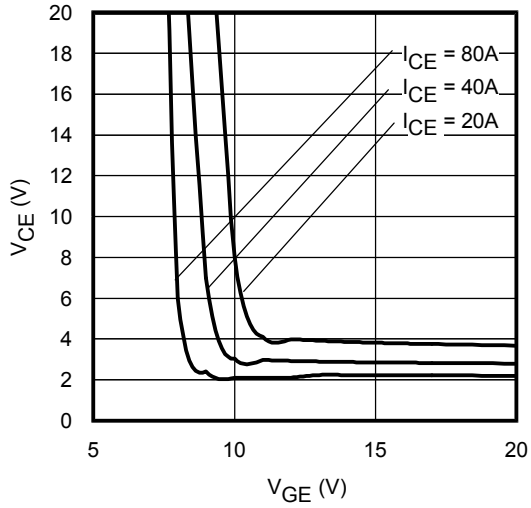
**Fig. 6 - Typ. IGBT Output Characteristics**  
 $T_J = 25^\circ\text{C}; t_p = 80\mu\text{s}$



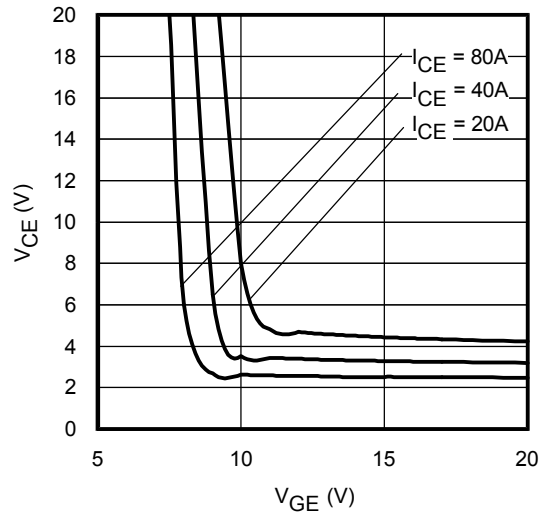
**Fig. 7 - Typ. IGBT Output Characteristics**  
 $T_J = 125^\circ\text{C}; t_p = 80\mu\text{s}$



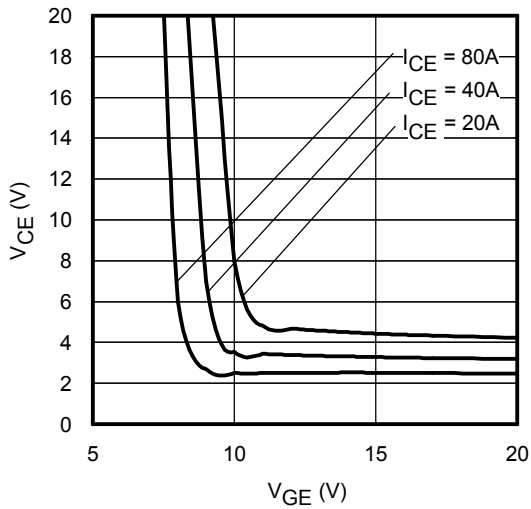
**Fig. 8 - Typ. Diode Forward Characteristics**  
 $t_p = 80\mu\text{s}$



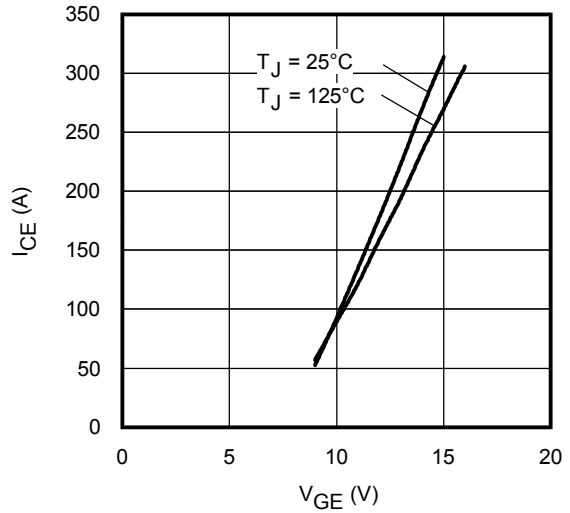
**Fig. 9** - Typical  $V_{CE}$  vs.  $V_{GE}$   
 $T_J = -40^\circ\text{C}$



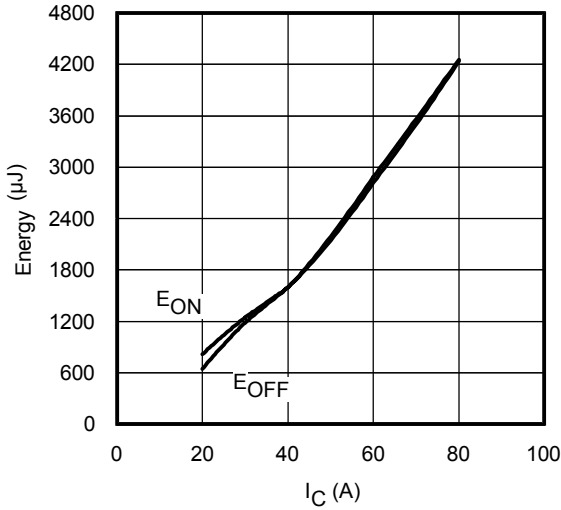
**Fig. 10** - Typical  $V_{CE}$  vs.  $V_{GE}$   
 $T_J = 25^\circ\text{C}$



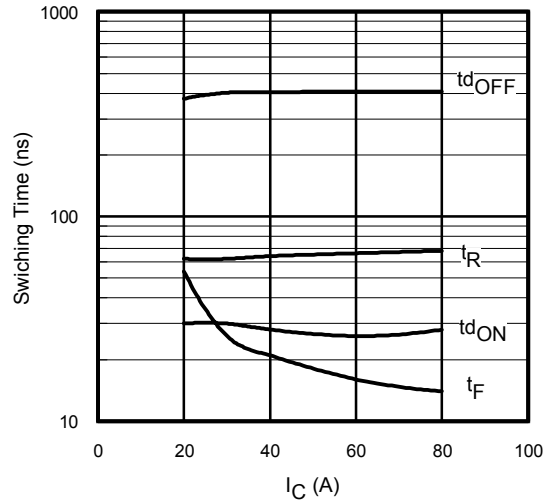
**Fig. 11** - Typical  $V_{CE}$  vs.  $V_{GE}$   
 $T_J = 125^\circ\text{C}$



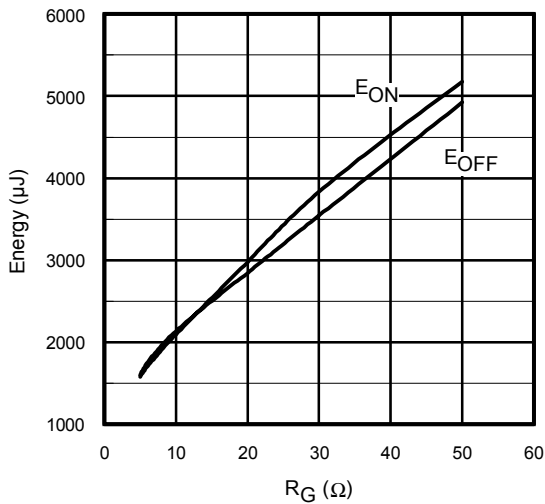
**Fig. 12** - Typ. Transfer Characteristics  
 $V_{CE} = 50\text{V}$ ;  $t_p = 10\mu\text{s}$



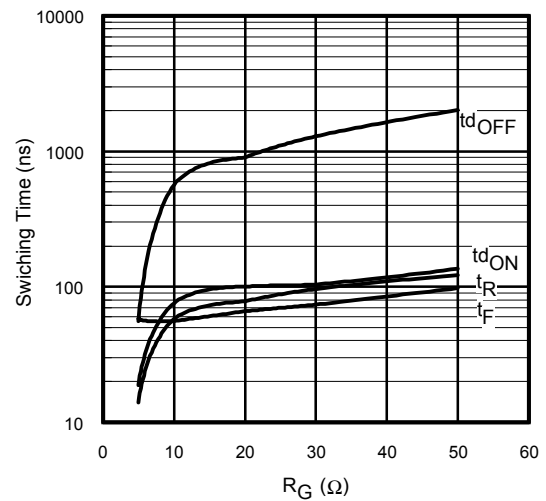
**Fig. 13** - Typ. Energy Loss vs.  $I_C$   
 $T_J = 125^\circ\text{C}$ ;  $L=250\mu\text{H}$ ;  $V_{CE}=400\text{V}$   
 $R_G=5\Omega$ ;  $V_{GE}=15\text{V}$



**Fig. 14** - Typ. Switching Time vs.  $I_C$   
 $T_J = 125^\circ\text{C}$ ;  $L=250\mu\text{H}$ ;  $V_{CE}=400\text{V}$   
 $R_G=5\Omega$ ;  $V_{GE}=15\text{V}$



**Fig. 15** - Typ. Energy Loss vs.  $R_G$   
 $T_J = 150^\circ\text{C}$ ;  $L=250\mu\text{H}$ ;  $V_{CE}=600\text{V}$   
 $I_{CE}=40\text{A}$ ;  $V_{GE}=15\text{V}$



**Fig. 16** - Typ. Switching Time vs.  $R_G$   
 $T_J = 150^\circ\text{C}$ ;  $L=250\mu\text{H}$ ;  $V_{CE}=600\text{V}$   
 $I_{CE}=40\text{A}$ ;  $V_{GE}=15\text{V}$

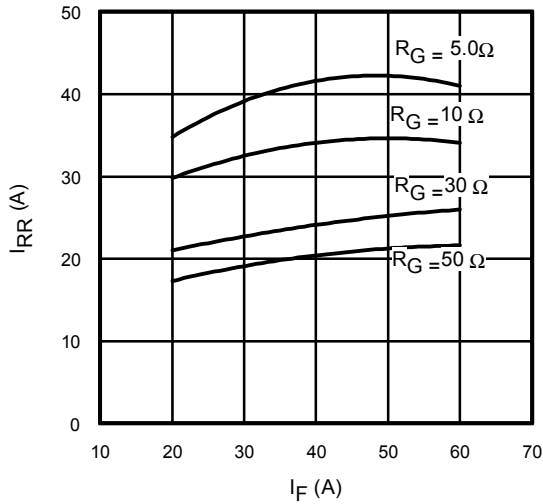


Fig. 17 - Typical Diode  $I_{RR}$  vs.  $I_F$   
 $T_J = 125^\circ\text{C}$

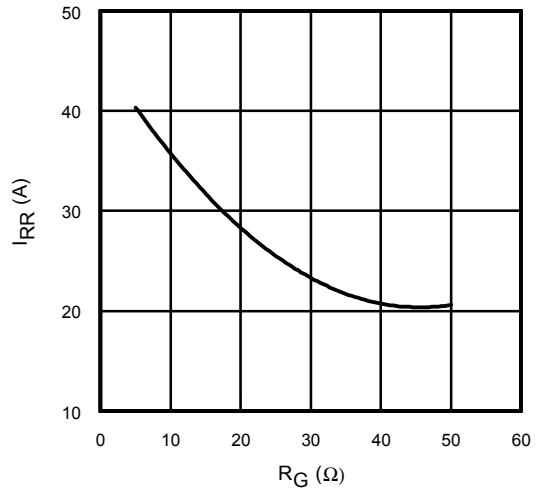


Fig. 18 - Typical Diode  $I_{RR}$  vs.  $R_G$   
 $T_J = 125^\circ\text{C}; I_F = 40\text{A}$

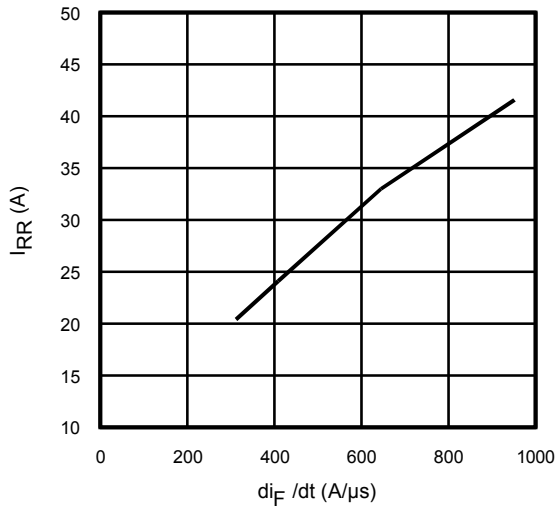


Fig. 19- Typical Diode  $I_{RR}$  vs.  $di_F/dt$   
 $V_{CC} = 600\text{V}; V_{GE} = 15\text{V};$   
 $I_{CE} = 40\text{A}; T_J = 125^\circ\text{C}$

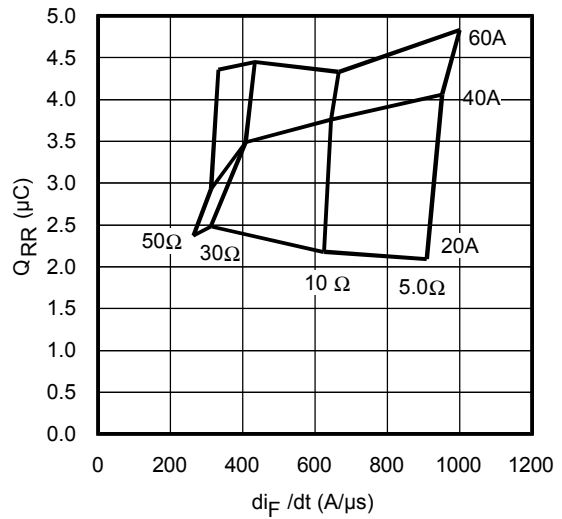
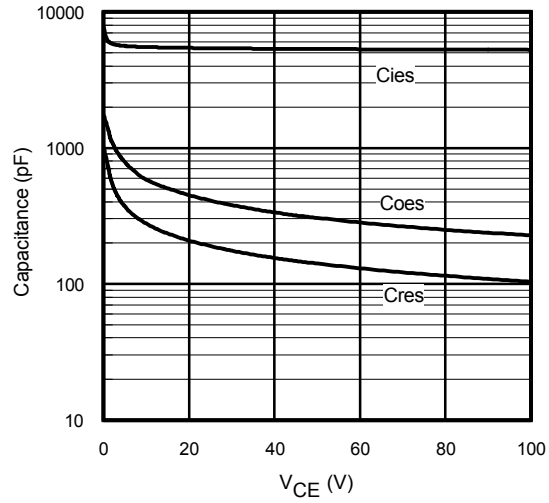
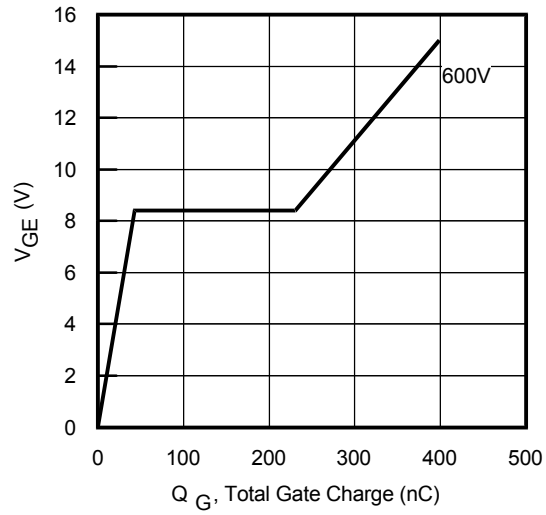


Fig. 20 - Typical Diode  $Q_{RR}$   
 $V_{CC} = 600\text{V}; V_{GE} = 15\text{V}; T_J = 125^\circ\text{C}$





**Fig. 21**- Typ. Capacitance vs. V<sub>CE</sub>  
 V<sub>GE</sub>= 0V; f = 1MHz



**Fig. 22** - Typical Gate Charge vs. V<sub>GE</sub>  
 I<sub>CE</sub> = 5.0A; L = 600μH

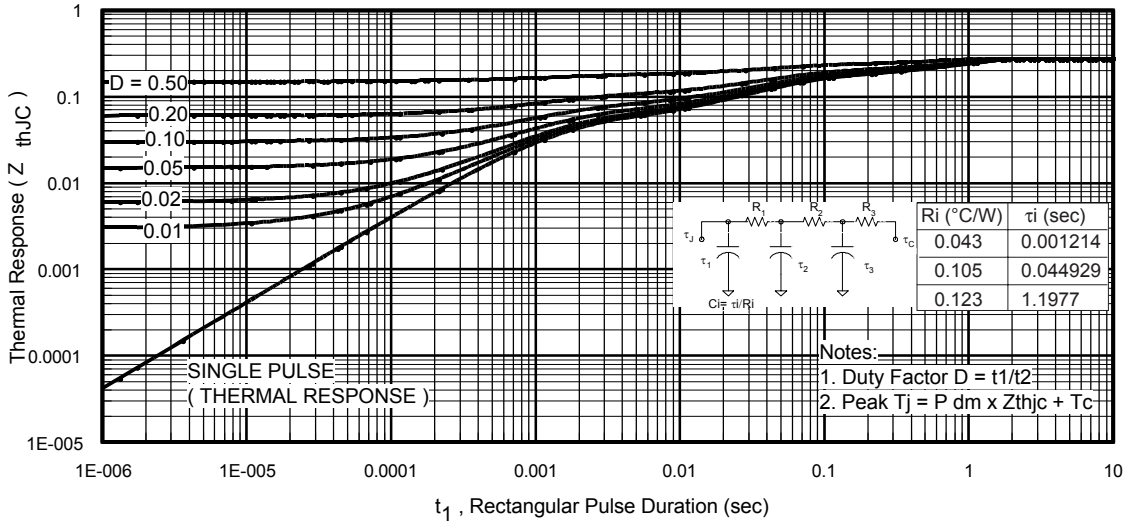


Fig 23. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

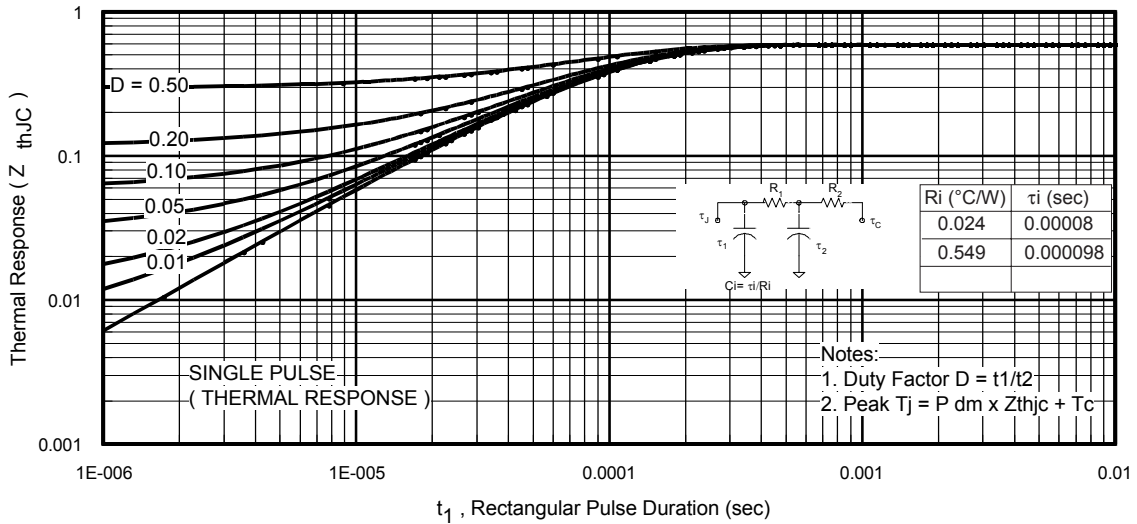


Fig 24. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

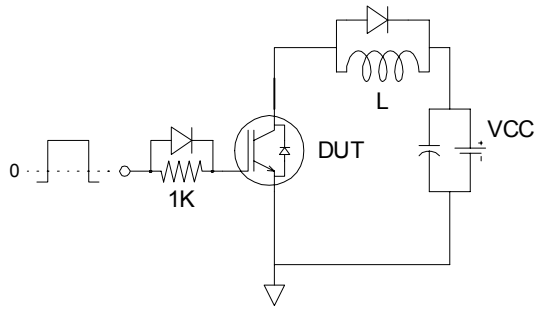


Fig. CT.1 - Gate Charge Circuit (turn-off)

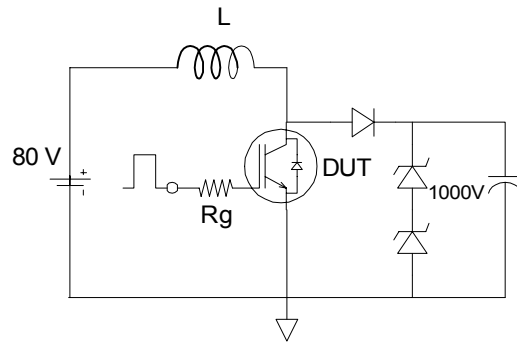


Fig. CT.2 - RBSOA Circuit

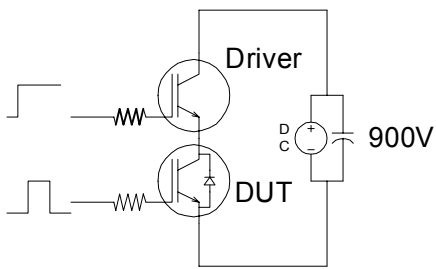


Fig. CT.3 - S.C. SOA Circuit

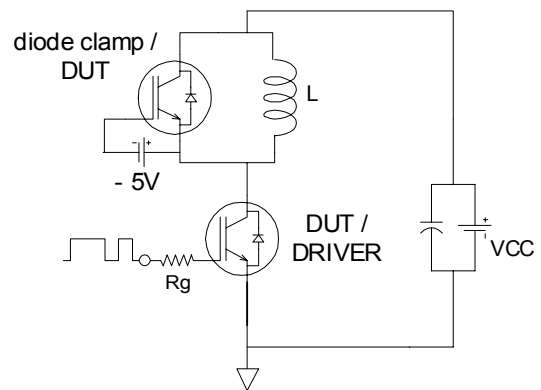
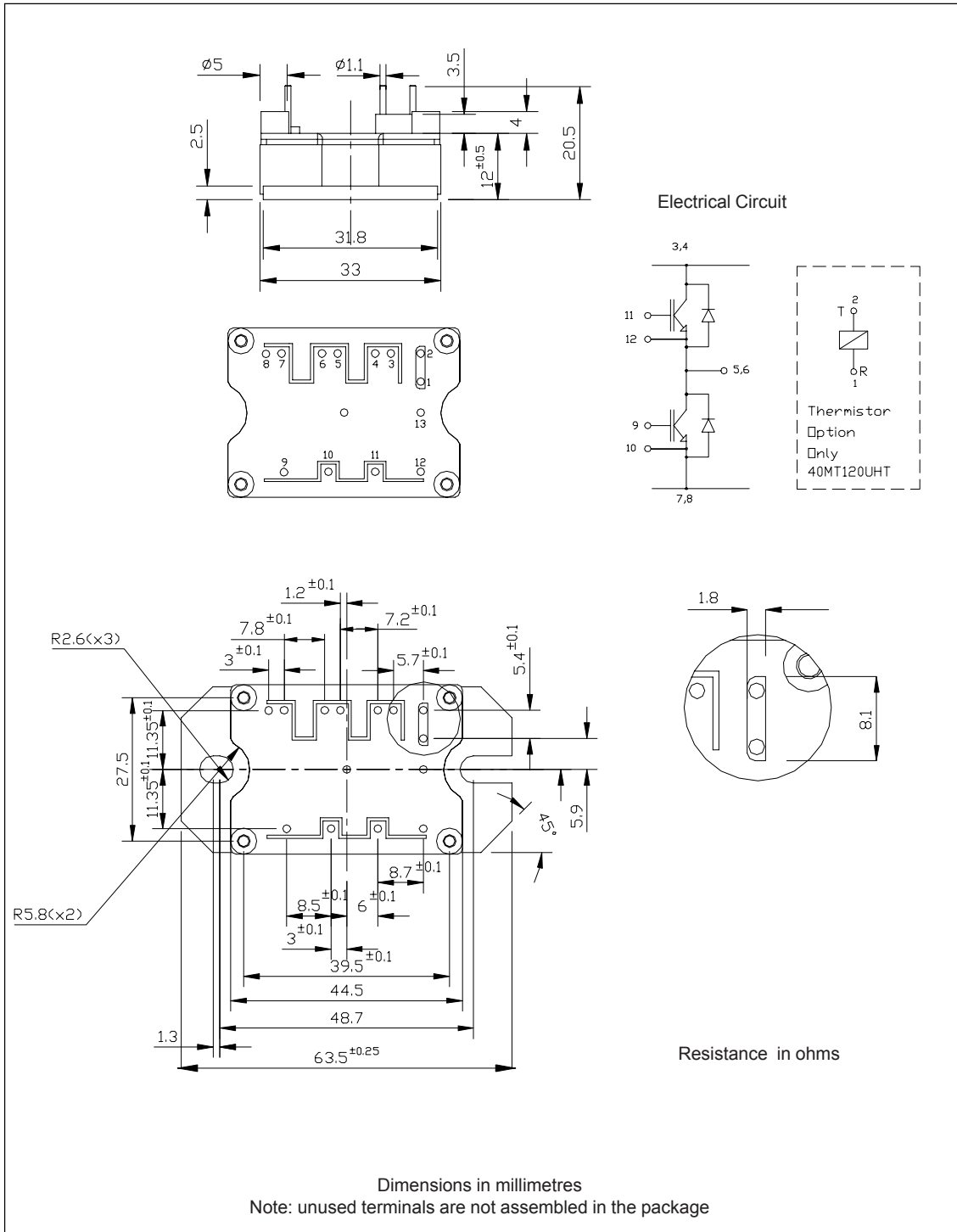


Fig. CT.4 - Switching Loss Circuit

**Outline Table**



### Ordering Information Table

| Device Code |    |
|-------------|----|
| 40          | MT |
| 120         | U  |
| H           | -  |
| ①           | ②  |
| ③           | ④  |
| ⑤           | ⑥  |

|   |  |
|---|--|
| <p><b>1</b> - Current rating (40 = 40A)</p> <p><b>2</b> - Essential Part Number</p> <p><b>3</b> - Voltage code (120 = 1200V)</p> <p><b>4</b> - Speed/ Type (U = Ultra Fast IGBT)</p> <p><b>5</b> - Circuit Configuration (H = Half Bridge)</p> <p><b>6</b> - Special Option</p> | <div style="border: 1px solid black; padding: 5px; display: inline-block;">                 Empty = no special option<br/>                 T = Thermistor             </div> |
|---|--|

Data and specifications subject to change without notice.  
 This product has been designed and qualified for Industrial Level.  
 Qualification Standards can be found on IR's Web site.